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PATENT
2565-0136P

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IN THE U.S. PATENT AND TRADEMARK OFFICE

APPLICANT: Shusou WADAKA et al. CONF NO.: 2419
APPL. NO.: 09/202,070 GROUP: 2834
FILED: December 8, 1998 EXAMINER: M. Budd
FOR: FILM ACOUSTIC WAVE DEVICE AND ITS MANUFACTURING
METHOD AND CIRCUIT DEVICE

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

February 21, 2002

Sir:

In response to the Office Action dated December 28, 2001, please amend the above-identified application as follows.

IN THE CLAIMS:

Please cancel claims 1, 15, 25 and 27-41 without prejudice or disclaimer to the subject matter contained therein.

Please replace claims 2-14 with the following.

2. (Three Times Amended) The wafer according to claim 42, wherein a length of the at least one upper electrode is dependent upon the position at which the film acoustic wave device is mounted on the wafer.

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